

Subst. Form PTO-1449

APPLICANT'S INFORMATION
DISCLOSURE STATEMENT

Atty. Docket No.: END920020084US1 (IEN-10-5695)

Serial No.: To be assigned

10/660,261

Applicant: Infantolino et al

Filing Date: Herewith

Group:

U.S. PATENT DOCUMENTS

Initial*		Document No.	Date	Name	Class	Subcl.	Filing Date
AR	AA	5,492,586	02/20/96	Gorczyca	156	245	06/24/94
I	AB	6,221,694 B1	04/24/01	Bhatt et al	438	122	06/29/99
I	AC	6,229,216 B1	05/08/01	Ma et al	257	777	01/11/99
	AD	6,271,469 B1	08/07/01	Ma et al	174	52.4	11/12/99
BM	AE	6,312,972 B1	11/06/01	Blackshear	438	106	08/09/99
	AF						
	AG						
	AH						
	AI						
	AJ						
	AK						

FOREIGN PATENT DOCUMENTS

		Document No.	Date	Country	Class	Subcl.	Translation?
AR	AL	JP11220061A	08/10/99	Japan			Abstract attached
	AM						
	AN						

OTHER DOCUMENTS

AR	AO	IBM Technical Disclosure Bulletin entitled "Flatpack Package Using Core Metal Layer of Composite Substrate as Ground Plane", March, 1991					
	AP						
	AQ						
	AR						
	AS						
	AT						

Examiner:

Date Considered:

05/02/04

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if in conformance and not considered. Include copy of this form with next communication to applicant

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